

Description

The STD10PF06 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = -60V I_D =-10 A

 $R_{DS(ON)} < 140 m\Omega @ V_{GS} = 10V$

Application

Brushless motor

Load switch

Uninterruptible power supply

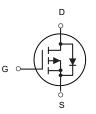
Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
STD10PF06	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units V	
Vds	Drain-Source Voltage	-60		
Vgs	Gate-Source Voltage	±20	V	
I⊳@Tc=25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-10	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-8.3	А	
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3.3	A	
I₀@T _A =70°C	Continuous Drain Current, V _{GS} @ -10V ¹ -2.7		A	
Ідм	Pulsed Drain Current ² -26		А	
EAS	Single Pulse Avalanche Energy ³	29.8	mJ	
las	Avalanche Current -24.4		А	
P₀@Tc=25°C	Total Power Dissipation ⁴ 31.3		W	
P _D @T _A =25°C	Total Power Dissipation ⁴	Total Power Dissipation ⁴ 2		
Тятд	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
R _{0JA}	Thermal Resistance Junction-Ambient ¹ 62		°C/W	
R _θ JC	Thermal Resistance Junction-Case ¹	4.0	°C/W	





P-Channel MOSFET

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V	
∆BVDSS/∆TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.03		V/°C	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-3A		125	140	mΩ	
	Static Drain-Source On-Acaistance	V _{GS} =-4.5V , I _D =-2A		185	200	11132	
VGS(th)	Gate Threshold Voltage	V_{GS} = V_{DS} , I_{D} =-250 uA	-1.2	1.6	-2.5	V	
IDSS	Drain Source Leekege Current	$V_{\text{DS}}\text{=-48V}$, $V_{\text{GS}}\text{=}0\text{V}$, $T_{\text{J}}\text{=}25^{\circ}\text{C}$			1		
1032	Drain-Source Leakage Current	V_{DS} =-48V , V_{GS} =0V , T_J =55°C			5	uA	
IGSS	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-3A		8.5		S	
Qg	Total Gate Charge (-4.5V)			12.1			
Qgs	Gate-Source Charge	V _{DS} =-48V , V _{GS} =-4.5V , I _D =-3A		2.2		nC	
Qgd	Gate-Drain Charge			6.3			
Td(on)	Turn-On Delay Time			9.2			
Tr	Rise Time	V _{DD} =-15V , V _{GS} =-10V ,		20.1		ns	
Td(off)	Turn-Off Delay Time	R _G =3.3□, I _D =-1A		46.7			
T _f	Fall Time			9.4			
Ciss	Input Capacitance			1137			
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		76		pF	
Crss	Reverse Transfer Capacitance			50			
IS	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current			-13	Α	
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , TJ=25℃			-1.2	V	

Note :

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.

2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3、The EAS data shows Max. rating . The test condition is V DD =-25V,V GS =-10V,L=0.1mH,IAS =-24A

 $4\,{\scriptstyle \sim}\,$ The power dissipation is limited by 150 $^\circ\!{\rm C}$ junction temperature

5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



P-Channel Typical Characteristics

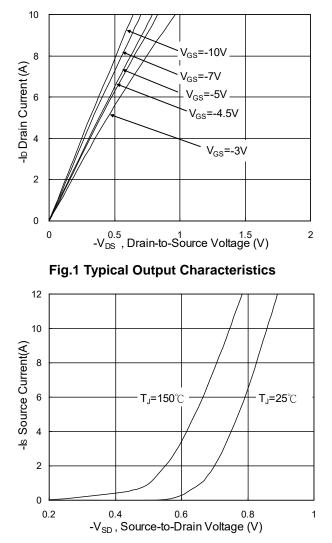


Fig.3 Forward Characteristics of Reverse

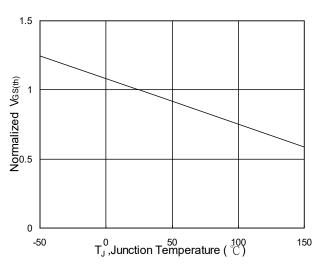


Fig.5 Normalized V_{GS(th)} v.s T_J

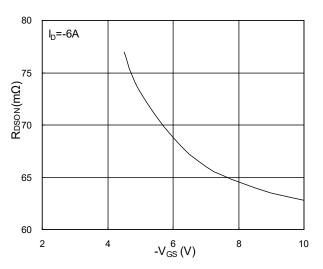


Fig.2 On-Resistance v.s Gate-Source

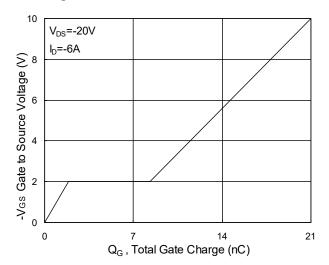


Fig.4 Gate-Charge Characteristics

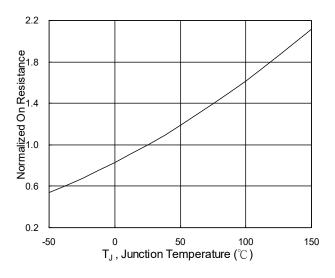


Fig.6 Normalized R_{DSON} v.s T_{J}



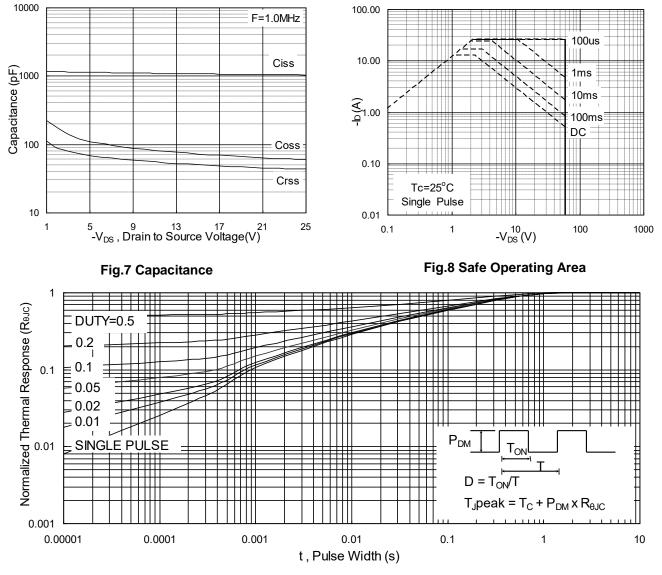


Fig.9 Normalized Maximum Transient Thermal Impedance

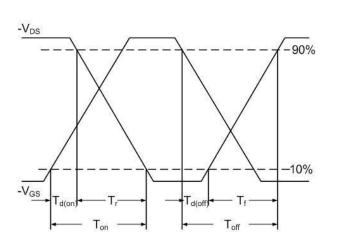


Fig.10 Switching Time Waveform

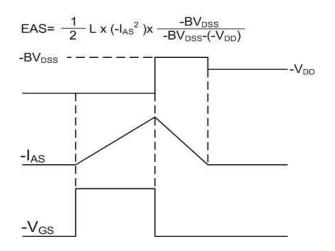
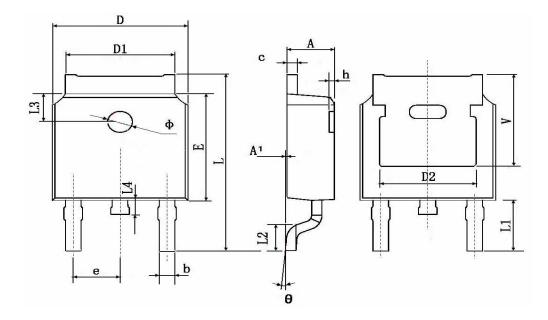


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3		1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0 °	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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